**Iphone (and others) touch controller replacement (343s0645 and bcm5976)**

**Removal**

1 remove the motherboard completely from the phone

2 secure the MB using a vice or other tool and protect the surrounding parts from excess heat by covering with kapton tape or metal shielding

3 use hot air set to 120deg low air flow and using a sharp needle or tweezers remove any adhesive/ black glue around the edges of the ic completely take as much time as possible for best results.

4 put flux on top and around the edges of the wifi ic to aid heat dispersion then using a 4/6mm nozzle and hot air at 380deg (air flow set to max) apply heat to the ic in a circular fashion for around 2 mins testing with a metal pick constantly until the chip is freely moving then remove the it from the pcb.

5 remove any traces of solder and clean the pads on the MB using flux and any one of the many methods currently demonstrated on the web I personally use braid impregnated with extra flux be extremely careful not to detach any of the pads on the pcb

**Refitting**

1/ apply flux to the pads on the motherboard

2/ place the ic into position on the pads of the motherboard the ic must be correctly oriented at this point apply flux to the top of the ic

3/ using a 4mm nozzle set to 310/320deg and max air flow place the hot air gun above the ic at a distance of around 150mm (heat the area of the ic until the flux can be seen to flow this is necessary to hold the ic in place) next move the heat to around 10/20mmfrom the ic , the external components must be protected from any heat at all times reflow of this ic should take around 30 to 45 seconds (see notes below)

Finally remove the heat and allow the MB to cool for approx. 5mins without moving it

(When the solder has flowed you should be able to nudge the ic slightly and it will move back into position of its) own accord

Important notes

The above instructions are for guidance only and computabench accepts no liability for breakdown or damage to components or pcb caused by untrained personnel

**https://www.youtube.com/watch?v=kNx76iyWQYo******

**hot air requires the air around the solder ball to be heated and therefore a higher than normal temp is necessary**

**for reflow**